



Mounting Instructions for Dual INT-A-PAK Low Profile Modules

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This application note introduces Vishay's Dual INT-A-PAK (DIAP) low-profile modules. It covers their key features and gives instructions for using heatsinks with the modules.

DIAP low-profile modules are designed to provide reliable performance in rugged 300 A to 400 A industrial applications. A single housing is used to integrate power components, providing higher power density. Various die selections are available in several configurations.

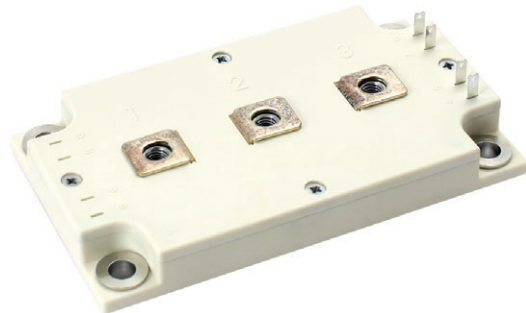


Fig. 1 - Example of a DIAP low-profile module

INTRODUCTION

Vishay's DIAP low-profile modules are distinguished by these key features:

- Fully isolated from the metal base, allowing common heatsink and compact assemblies to be built
- Wire-bonded internal connections
- Screwable electrical terminals secured against axial pull-outs. They are fixed to the module housing via a click-stop feature
- Low junction-to-case thermal resistance

Important factors in the assembly process are:

- Heatsink design
- Power leads size / area
- Distance from adjacent heating parts
- Protection against electrostatic discharge (ESD)

Recommendations for each of these items and requirements for mounting DIAP low-profile modules to the heatsink are discussed in the following sections.

ESD PROTECTION

IGBT, MOSFET, and diode modules are sensitive to ESD. All DIAP low-profile modules are protected against ESD during shipment; they are separated in a carton box and protected by an antistatic sponge. Anyone handling or working with the modules during the assembly process must wear a conductive grounded wristband.

HEATSINK SPECIFICATION

The contact surface of the heatsink must be flat, with a recommended tolerance of < 0.03 mm (< 1.18 mils) and a levelling depth (surface roughness) of < 0.02 mm (< 0.79 mils), according to DIN / ISO 1302. In general, a milled or machined surface is satisfactory if prepared with tools in good working condition. The heatsink mounting surface must be clean, with no dirt, corrosion, or surface oxides. It is very important to keep the mounting surface free from particles exceeding 0.05 mm (2 mils) in thickness.

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THERMAL COMPOUND

Coat the heatsink surface and the power module base plate uniformly with a good quality thermal compound. Apply uniform pressure on the package to force the compound to spread over the entire contact area. The purpose of thermal grease is to fill gaps at the base plate/heatsink interface, and its use is recommended to ensure low case-to-sink thermal resistance. The thermal conductivity of the compound should be not less than 0.5 W/mK. The suggested thermal grease is DC340 (Dow Corning), silicone-free HTCP (Electrolube), or an equivalent. Screen printing and rubber rolling are the preferred methods for applying the grease. A final grease layer thickness in the range of 80 µm to 100 µm is considered suitable for most applications.

MOUNTING TO HEATSINK

Confirm that there are not any foreign particles on the surface of the screen tooling and plate. Place a suitable amount of thermal compound on the plate and spread it equably by using a roller or spatula. Thermal grease contact and distribution will be improved during the first hours and after heating up the system for the first time.

Bolt the module to the heatsink using the fixing holes. An even amount of torque should be applied for each individual mounting screw. For proper mounting, it is recommended to use M6 screws secured by a lock washer and flat washer. Please refer to each individual data sheet to find the maximum torque that can be applied. A torque wrench that is accurate in the specified range must be used in mounting the module to achieve optimum results.

The minimum suggested thread depth is 10 mm to 11 mm (0.40 in to 0.43 in) in heatsinks. All mounting holes should be free of burrs. The first mounting screw should be tightened to one third of the recommended torque; the second screw should then be tightened to the same torque. Screws should be mounted in a crosswise sequence. For example, if the fixing holes are 1, 2, 3, and 4 in a clockwise or counter-clockwise sequence, then we suggest mounting the screws in the following order: 1 and 3, then 2 and 4.

Over-tightening the mounting screw may lead to deformation of the package, which would hence increase the thermal resistance and damage the semiconductors. After a period of three hours, check the torque with a final tightening in the opposite sequence to allow the spread of the compound.

POWER LEADS OR BUS BARS CONNECTION

An even amount of torque should be applied for each individual screw. For proper connection, it is recommended to use M5 screws secured by a lock washer and flat washer. The maximum thread depth into the module mounting studs should conform to each individual package outline drawing in the datasheet. Also refer to each individual data sheet to find the maximum torque that can be applied. A torque wrench that is accurate in the specified range must be used in fixing screws of the power leads or bus bars to achieve optimum results.

SIGNAL TERMINAL AND HOUSING CONNECTION

We recommend using receptacle fast-on terminals (for 2.8 x 0.5 tab (series 110) ref. PN.AMP 42067-1 or equivalent) and tinned copper stranded cable (UL 758, style 1558, AWG 22 (0.32 mm²) laid 19 x 0.16 ETFE insulation, ext. dia. 1.25 mm, temperature rating 125 °C) (Fig. 2).

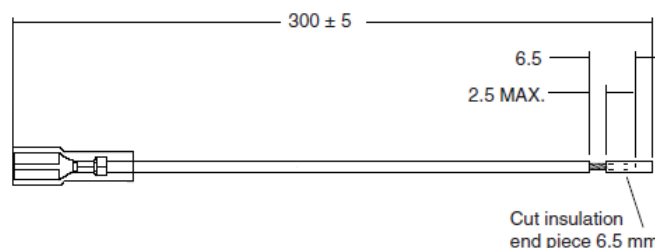


Fig. 2

END OF LIFE MODULE WASTE DISPOSAL RECOMMENDATION

Corporate social responsibility is more and more important for the environment protection, Vishay is certified by ISO 140001 and Vishay modules are always compliant with the Restriction of Hazardous Substances in Electrical and Electronic Equipment (RoHS) directive.

We recommend that the end of life modules (include components of the modules) shall be segregated by hazardous and collected in a labeled container (refer to CER code # 16.02.16) which should be put in a designated place.